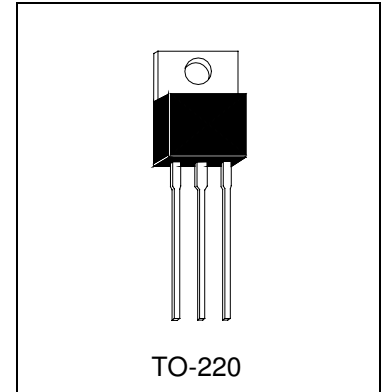




# HTIP41C

NPN EPITAXIAL PLANAR TRANSISTOR



## Description

The HTIP41C is designed for use in general purpose amplifier and switching applications.

## Absolute Maximum Ratings (T<sub>A</sub>=25°C)

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (T<sub>C</sub>=25°C) ..... 65 W  
Total Power Dissipation (T<sub>A</sub>=25°C) ..... 2 W
- Maximum Voltages and Currents  
BV<sub>CBO</sub> Collector to Base Voltage ..... 100 V  
BV<sub>CEO</sub> Collector to Emitter Voltage ..... 100 V  
I<sub>C</sub> Collector Current ..... 6 A

## Electrical Characteristics (T<sub>A</sub>=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV <sub>CBO</sub>	100	-	-	V	I <sub>C</sub> =1mA, I <sub>E</sub> =0
BV <sub>CEO</sub>	100	-	-	V	I <sub>C</sub> =30mA, I <sub>B</sub> =0
I <sub>CES</sub>	-	-	400	uA	V <sub>CE</sub> =100V, I <sub>B</sub> =0
I <sub>CEO</sub>	-	-	700	uA	V <sub>CE</sub> =60V, I <sub>B</sub> =0
I <sub>EBO</sub>	-	-	1	mA	V <sub>EB</sub> =5V, I <sub>C</sub> =0
*V <sub>CE(sat)</sub>	-	-	1.5	V	I <sub>C</sub> =6A, I <sub>B</sub> =600mA
*V <sub>BE(on)</sub>	-	-	2	V	I <sub>C</sub> =6A, V <sub>CE</sub> =4V
*h <sub>FE1</sub>	30	-	-		I <sub>C</sub> =0.3A, V <sub>CE</sub> =4V
*h <sub>FE2</sub>	15	-	75		I <sub>C</sub> =3A, V <sub>CE</sub> =4V
f <sub>T</sub>	3	-	-	MHZ	V <sub>CE</sub> =10V, I <sub>C</sub> =500mA, f=1MHz

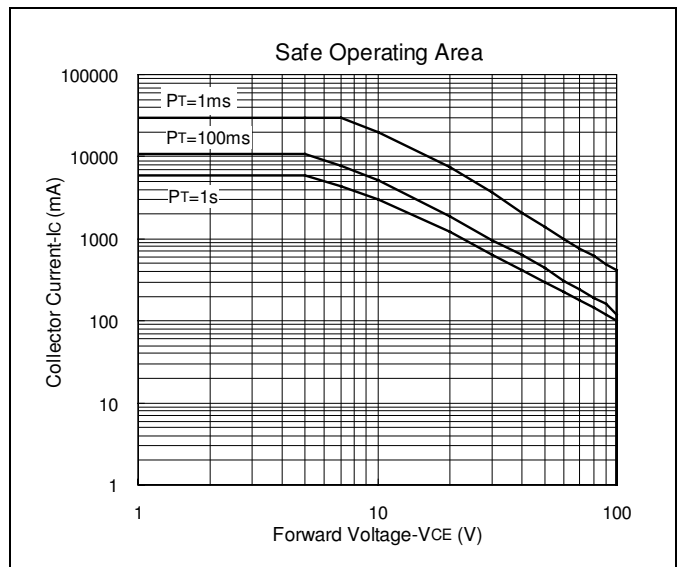
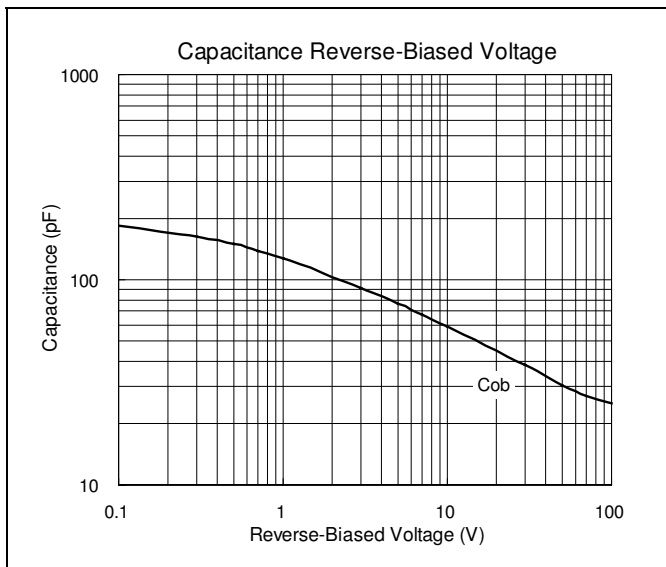
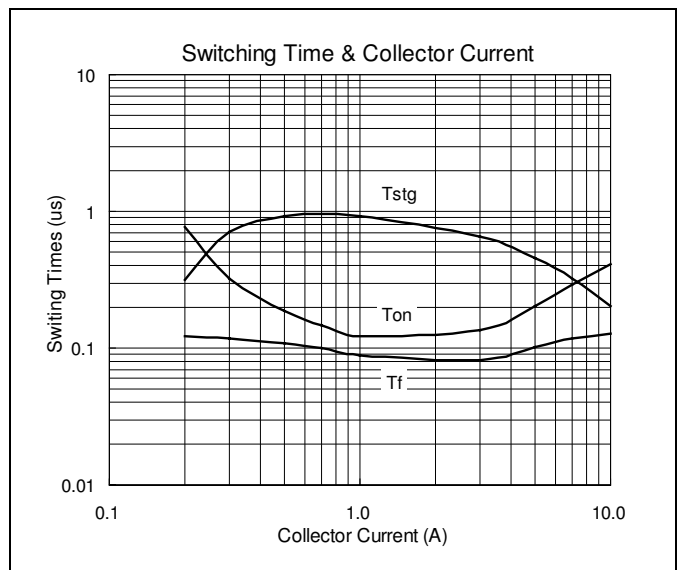
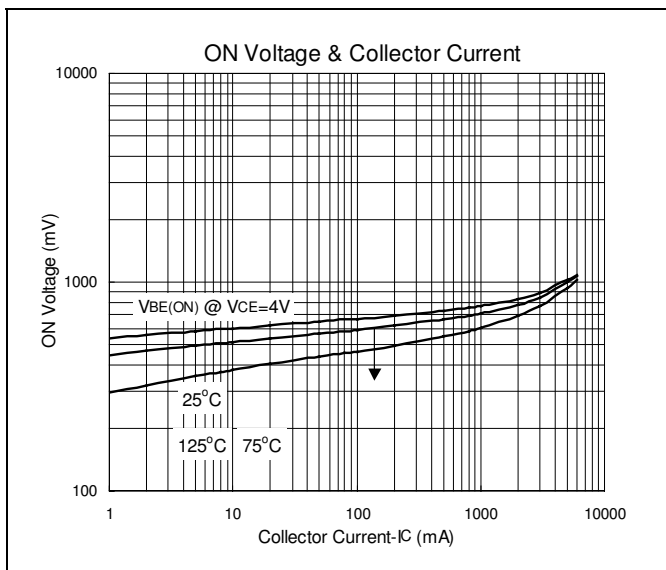
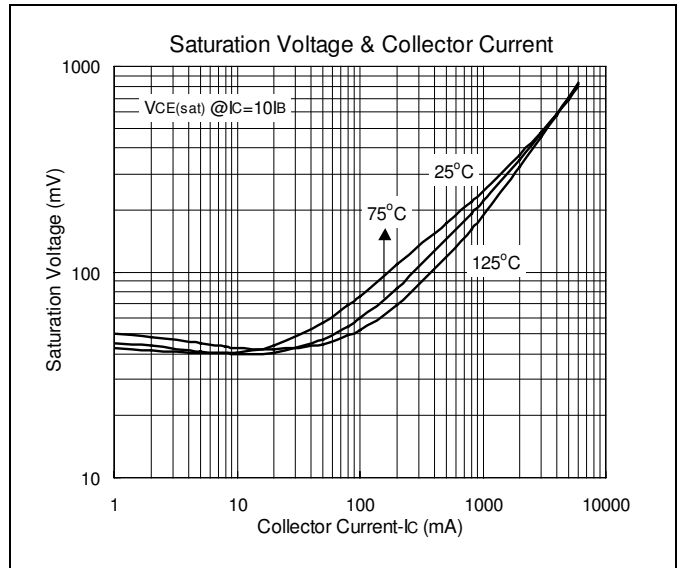
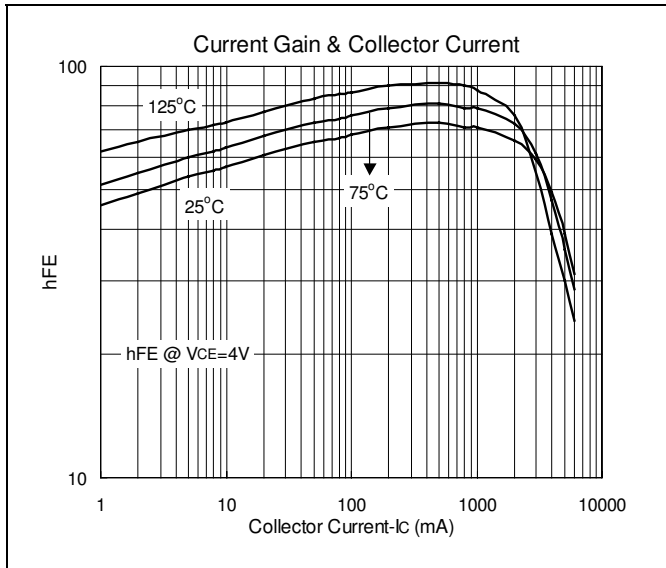
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

## Classification Of h<sub>FE2</sub>

Rank	A	B
h <sub>FE2</sub>	15-50	40-75



### Characteristics Curve





### TO-220AB Dimension

3-Lead TO-220AB  
 Plastic Package  
 HSMC Package Code: E

**Marking:**

Pb Free Mark  
 Pb-Free: "•" (Note)  
 Normal: None

Date Code      Control Code

Note: Green label is used for pb-free packing  
 Pin Style: 1.Base 2 & Tab.Collector 3.Emitter  
 Material:  
 • Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)  
 • Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	5.58	7.49
B	8.38	8.90
C	4.40	4.70
D	1.15	1.39
E	0.35	0.60
F	2.03	2.92
G	9.66	10.28
H	-	*16.25
I	-	*3.83
J	3.00	4.00
K	0.75	0.95
L	2.54	3.42
M	1.14	1.40
N	-	*2.54
O	12.70	14.27
P	14.48	15.87

\*: Typical, Unit: mm

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### Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T <sub>L</sub> to T <sub>p</sub> )	<3°C/sec	<3°C/sec
Preheat		
- Temperature Min (T <sub>smin</sub> )	100°C	150°C
- Temperature Max (T <sub>smax</sub> )	150°C	200°C
- Time (min to max) (ts)	60~120 sec	60~180 sec
T <sub>smax</sub> to T <sub>L</sub>		
- Ramp-up Rate	<3°C/sec	<3°C/sec
Time maintained above:		
- Temperature (T <sub>L</sub> )	183°C	217°C
- Time (t <sub>L</sub> )	60~150 sec	60~150 sec
Peak Temperature (T <sub>p</sub> )	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t <sub>p</sub> )	10~30 sec	20~40 sec
Ramp-down Rate	<6°C/sec	<6°C/sec
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

### 3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec